

Features

- 1 Ultra Low profile 1.18mm height
- 2 Incorrect card insertion prevention
- 3 Card fly-out prevention
- 4 Card detection switch
- 5 Easy inspection with exposed contact design



nano SIM



Push / Push



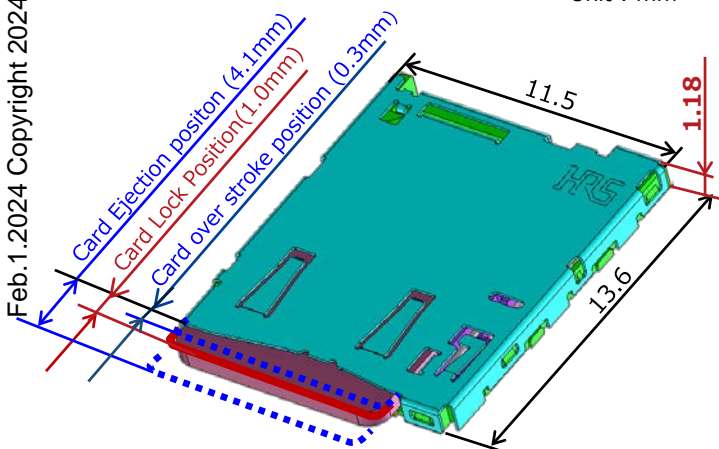
Ultra Low Profile

The world's lowest profile in its Class
1.18 mm

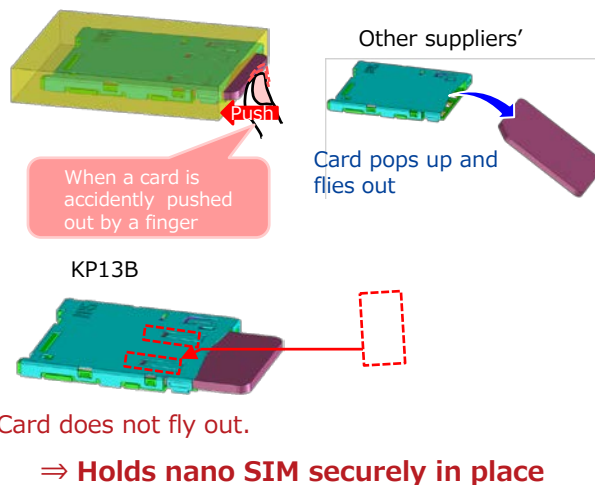
*As push-push type micro SIM card connector as of Feb. 2017

Dimensions

Unit : mm



Prevents card fly-out



Specifications

Contact Resistance	100mΩ Max.
Withstanding Voltage	500V AC for 1 minute
Mold Resistance	1,000MΩ Min. (500V DC)
Rated Current	0.5A
Rated Voltage	10V AC
Operating Temperature	-30°C to +85°C
Mating cycles	5,000 times

• RoHS compliant, Halogen-free product*

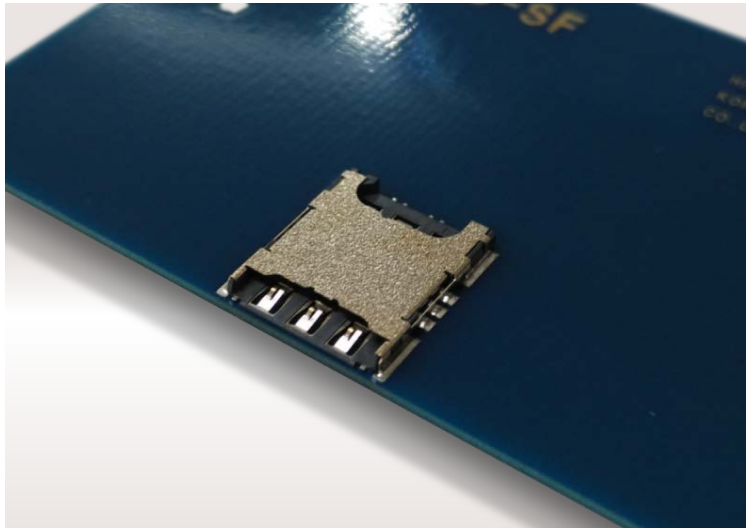
*This product satisfies halogen free requirements defined as 900ppm maximum chlorine, 900ppm maximum bromine, and 1500ppm maximum total of chlorine and bromine

※ Please contact Hirose's sales representative prior to adopting the products to in-vehicle devices.



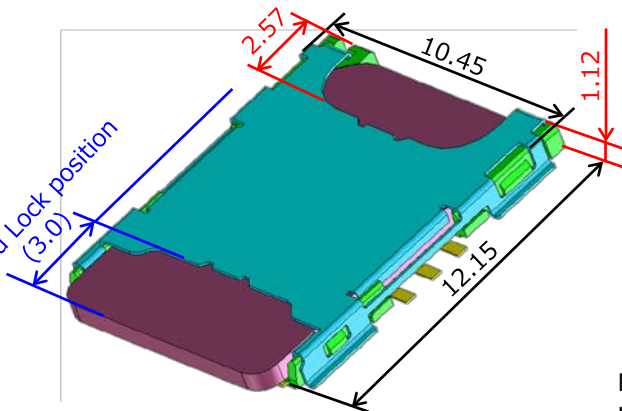
Features

- 1 **Low profile 1.12mm height**
- 2 **Designed to release card from the rear of the socket**
- 3 **Incorrect card insertion prevention**
- 4 **Contact damage prevention**
- 5 **Easy inspection with exposed contact design**

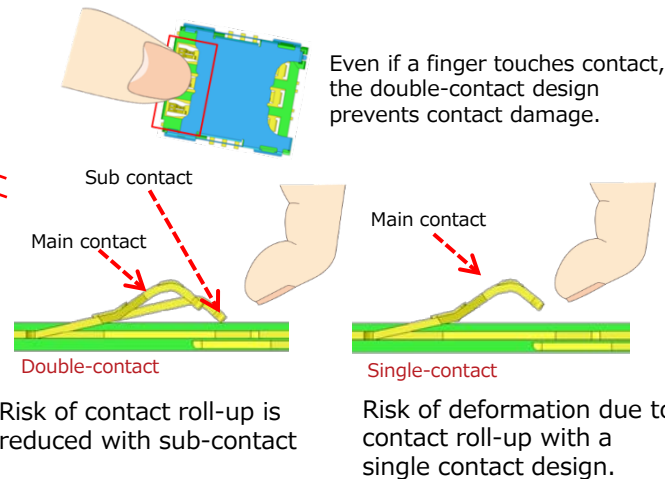


Dimensions

Unit : mm



Buckling prevention Design



Specifications

Contact Resistance	100mΩ Max.
Withstanding Voltage	500V AC for 1 minute
Mold Resistance	1,000MΩ Min. (500V DC)
Rated Current	0.5A
Rated Voltage	10V AC
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nano SIM



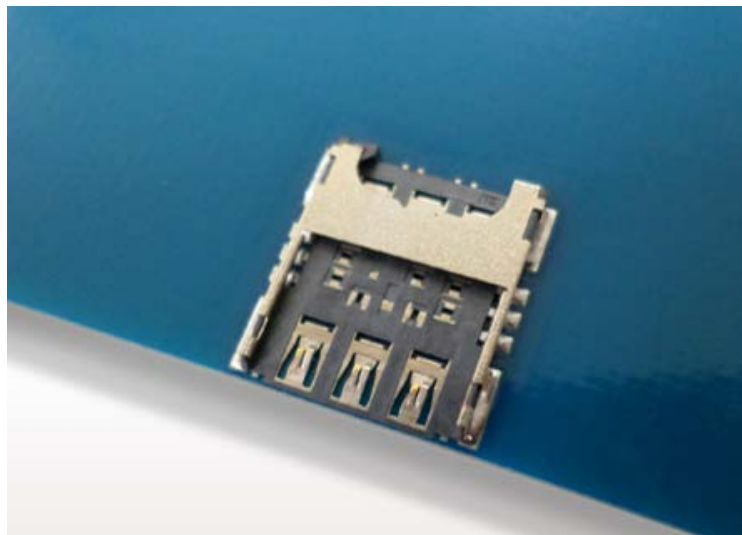
Push / Pull



Low Profile

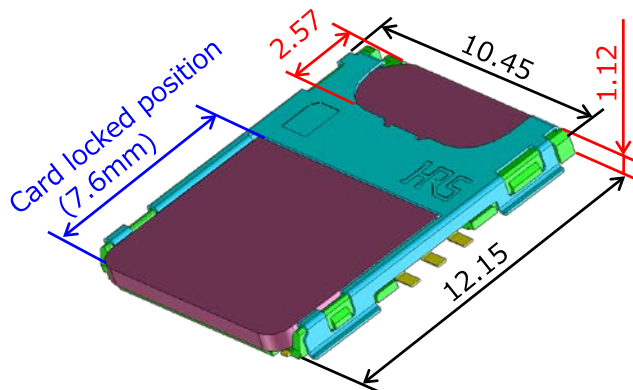
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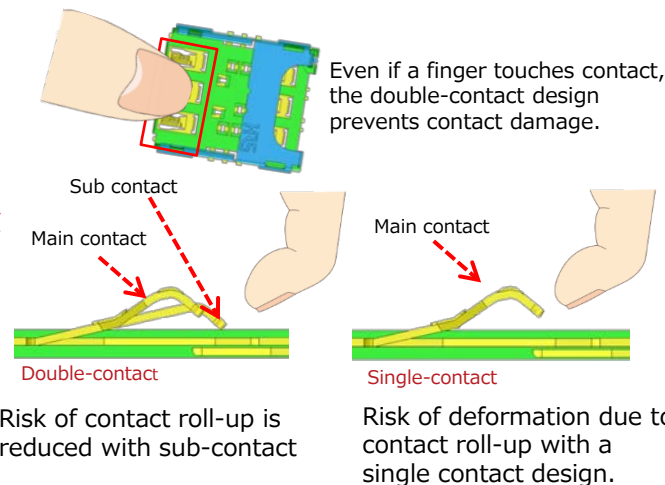


Dimensions

Unit : mm



Buckling prevention Design



Specifications

Contact Resistance	100mΩ Max.
Withstanding Voltage	500V AC for 1 minute
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Rated Voltage	10V AC
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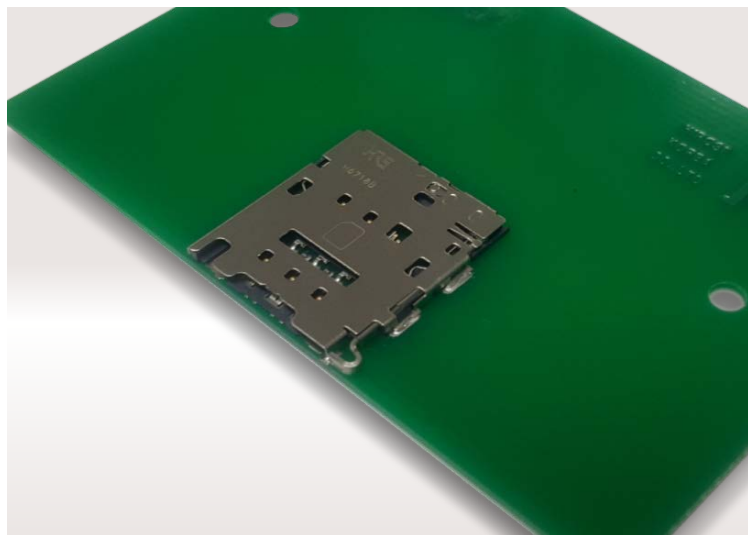
nano SIM

Tray

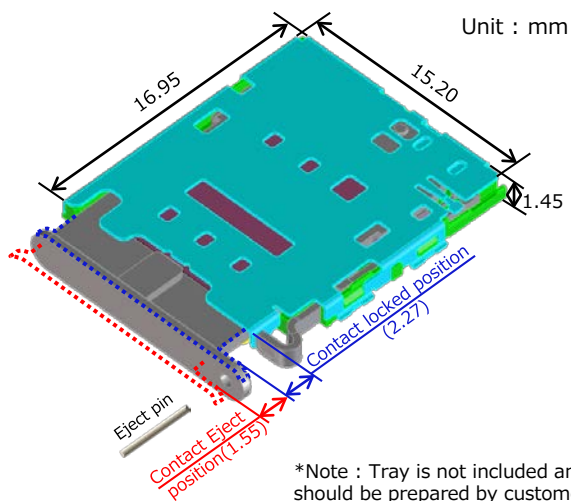
Low Profile

Features

- 1 **Easy to remove tray with eject pin**
- 2 **Buckling prevention eliminates contact damage**
- 3 **Enhanced retention force with dual side latches**
- 4 **Card detection switch**
- 5 **Easy inspection by exposed contact design**

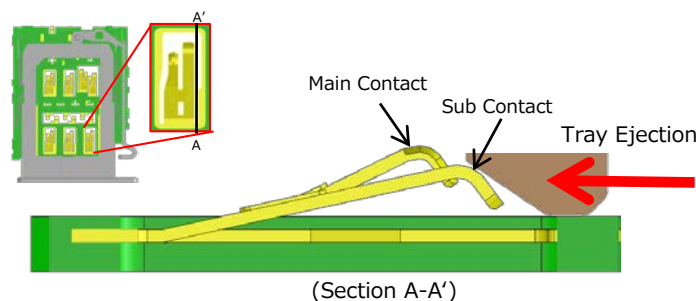


Dimensions



*Note : Tray is not included and should be prepared by customers.

Buckling prevention design



Dual-contact design allows the longer contact to reach tray first, and then the shorter contact smoothly moves along with it. When the tray passes on the main contact, there is no contact buckling.

Specifications

Contact Resistance	100mΩ Max.
Withstanding Voltage	500V AC for 1 minute
Mold Resistance	1,000MΩ Min. (500V DC)
Rated Current	0.5A
Rated Voltage	10V AC
Operating Temperature	-30℃ to +85℃
Mating cycles	3,000 times

• RoHS compliant, Halogen-free product*

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